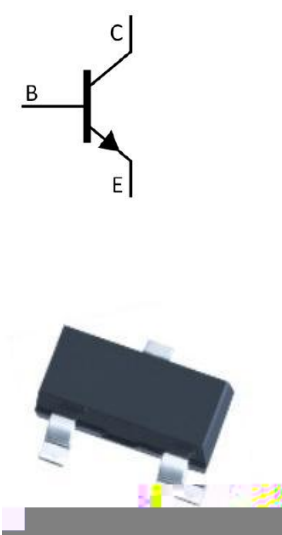


/ Descriptions

SOT-23 NPN Silicon NPN transistor in a SOT-23 Plastic Package.

Low current, Low voltage,HF Product.

General purpose amplifier and switching.



PIN 1 Base PIN 2 Emitter

/ h_{FE} Classification

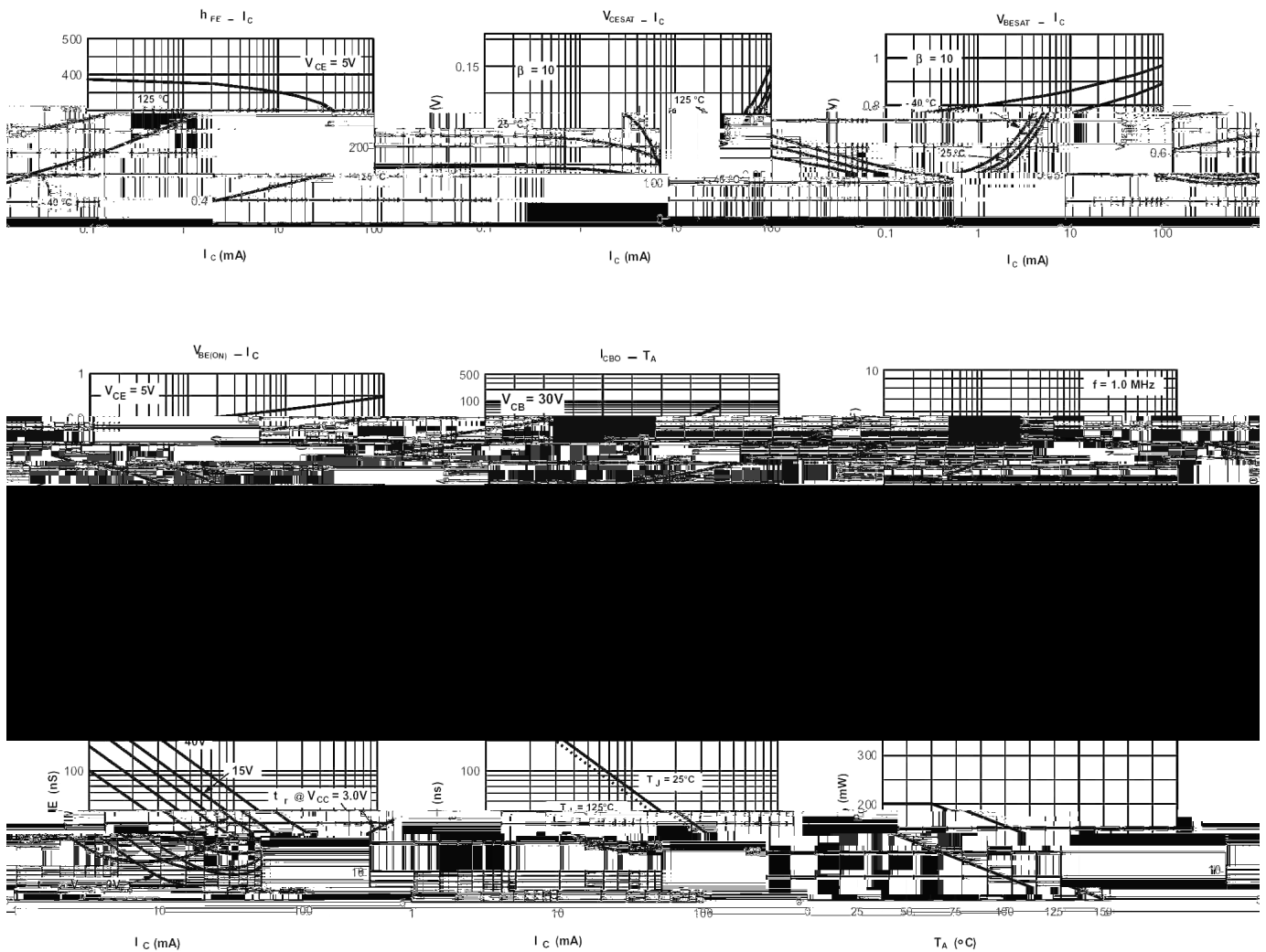
h_{FE} Range	100~
Marking	

Parameter	Symbol	Rating	Unit
Collector to Base Voltage	V_{CBO}	60	V
Collector to Emitter Voltage	V_{CEO}	40	V
Emitter to Base Voltage	V_{EBO}	6.0	V
Collector Current	I_C	200	mA
Collector Power Dissipation	P_C	200	mW
Collector Power Dissipation	$*P_C$	350	mW
Junction Temperature	T_j	150	°C
Storage Temperature Range	T_{stg}	-55~150	°C

* 7×5×0.6mm *When mounted on a 7×5×0.6mm ceramic board

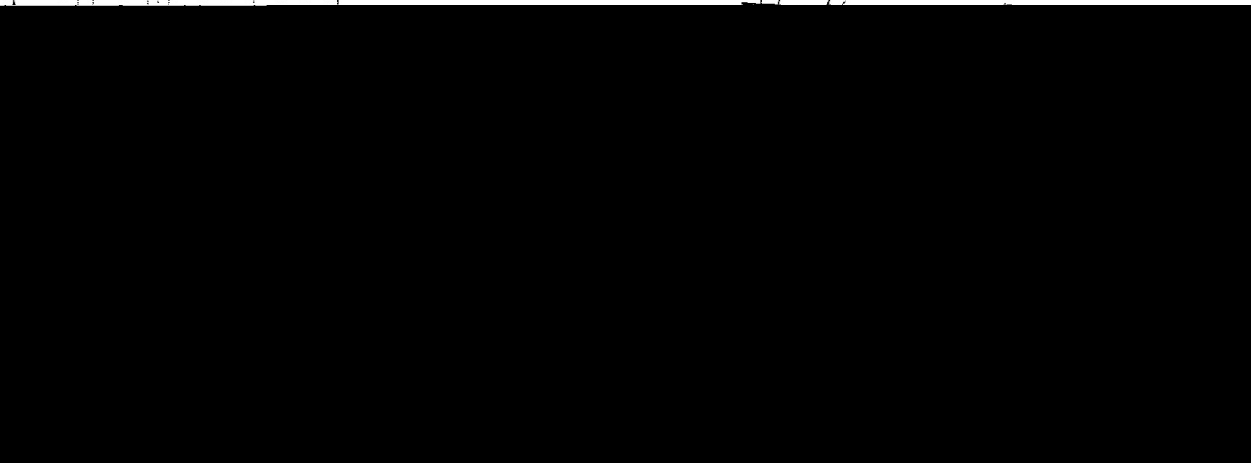
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Collector to Base Breakdown Voltage	V_{CBR}	$I_C = 10\mu A, V_{CE} = 10V, f = 1kHz$				V

/ Electrical Characteristic Curve



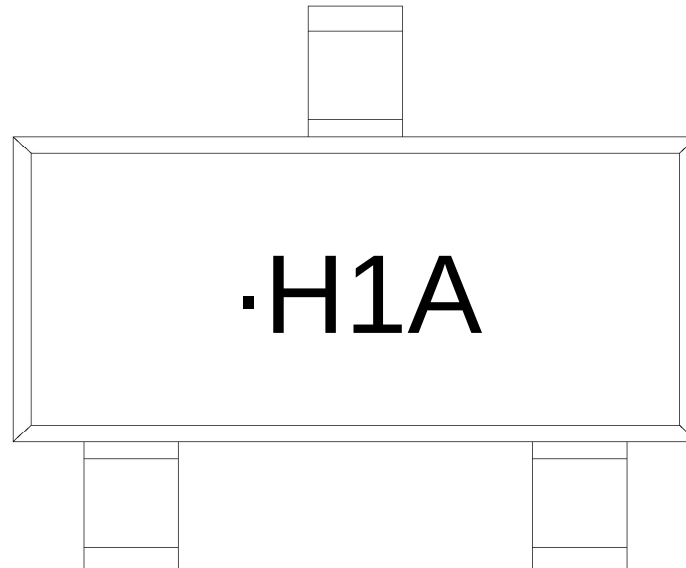
/ Package Dimensions

OUTLINE DIMENSIONS



Symbol	Dimensions in Millimeters		Symbol	Dimensions in Millimeters	
	Min	Max		Min	Max
1	0.45	0.65	2	0.97	1.20
3	2.70	3.40	4	0.25	0.35
5	7.0	8.0	6	0.20	0.30
7	1.85	2.15	8	7.0	8.0
9	0.35	0.55			

/ Marking Instructions



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H

1A

Note:

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Identify

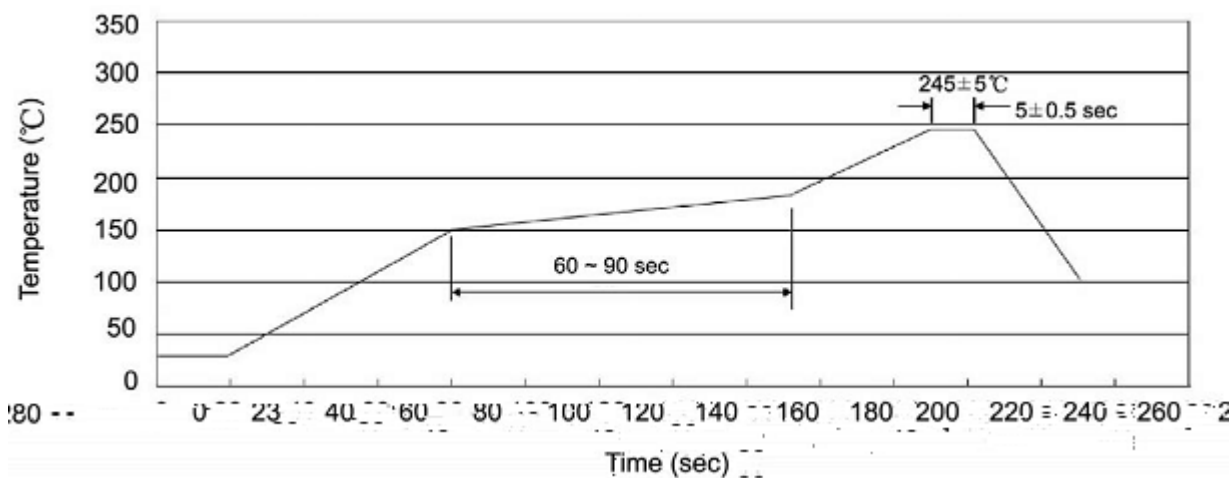
H

Company Code

1A

Product Type Code

() / Temperature Profile for IR Reflow Soldering(Pb-Free)



说明：

- 1、预热温度 25 ~ 150°C，时间 60 ~ 90sec;
- 2、峰值温度 245±5°C，时间持续为 5±0.5sec;
- 3、焊接制程冷却速度为 2 ~ 10°C/sec.

Note:

- 1.Preheating:25~150°C, Time:60~90sec.
- 2.Peak Temp.:245±5°C, Duration:5±0.5sec.
3. Cooling Speed: 2~10°C/sec.

/ Resistance to Soldering Heat Test Conditions

温度：260±5°C

时间：10±1 sec.

Temp.:260±5°C

Time:10±1 sec

/ Packaging SPEC.

卷盘包装 / REEL

Package Type	Units	Dimension	(unit mm ³)
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